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SEARCH REQUEST FORM

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Requester's Full Name Art Unit: 1745 Pho Mail Box and Bldg/Room Loc	tian Merca one Number 305 - Cartion: 8 E.C.2	Examiner #: 75795 Date: 9/11 Serial Number: 10/00#/2 Results Format Preferred (circle): PAPER DISK	8
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		oritize searches in order of need.	
utility of the invention. Define any to known. Please attach a copy of the co	erms that may have a speci- over sheet, pertinent claims	cribe as specifically as possible the subject matter to be sea acronyms, and registry numbers, and combine with the cor al meaning. Give examples or relevant citations, authors, and abstract.	ncept or etc, if
Title of Invention: Metho	& for male	, water - pair having sealed	0
Inventors (please provide full name	1 = 11/20 Q	Tage diales search	! Lh.
inventors (please provide full name	s): 10. Wood	Jeffrey Rielly, Robert	Hus
P. II.	2/200	,	
	3/1988	<u> </u>	
For Sequence Searches Only Please in appropriate serial number.	iclude all pertinent informati	ion (parent, child, divisional, or issued patent numbers) along y	with the
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Searcher Location:	AA Sequence (#)Structure (#)	Dialog	
Date Searcher Picked Up: 9 11		Questel/Orbit	
Date Completed:	Bibliographic Litigation	Dr.Link 40.00	
Searcher Prep & Review Time:		Lexis/Nexis	
Clerical Prep Time:	Fulltext	Sequence Systems	
Online Time:	Patent Family	WWW/Internet	
	Other	Other (specify)	

PTO-1590 (8-01)

Curr nt session 11/09/2002

(C) QUESTEL 1994

QUESTEL.ORBIT (TM) 1998 Last connection: 11/09/02 17*18*19

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22,03,02 1, 10 13

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Query/Command: FILE PLUSPAT

QUESTEL - Time in minutes : 0,69

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New Patent Citation Commands & FAM Citation Report - see INFO PATCITE Last update of file: 2002/09/11 (YYYY/MM/DD) 2002-36/UP (basic update)

Search statement 1

Query/Command: US6036872/PN

** SS 1: Results 1

Search statement 2

Query/Command: PRT FULL NONSTOP LEGALALL

1/1 PLUSPAT - @QUESTEL-ORBIT

PN - US6036872 A 20000314 [US6036872]

TI - (A) Method for making a wafer-pair having sealed chambers

PA - (A) HONEYWELL INC (US)

IN - (A) WOOD R ANDREW (US); RIDLEY JEFFREY A (US); HIGASHI ROBERT E (US)

AP - US5264598 19980331 [1998US-0052645]

PR - US5264598 19980331 [1998US-0052645]

IC - (A) C23F-001/00

EC - B81B-001/00 H01L-027/16

PCL - ORIGINAL (O): 216002000; CROSS-REFERENCE (X): 216024000 216033000 216039000 216056000 438054000 438456000 438700000 438703000

DT - Corresponding document

CT - US4701424; US5366587; US5528452; US5585311; US5851631

STG - (A) United States patent

AB - A method for fabricating a wafer-pair having at least one recess in one wafer and the recess formed into a chamber with the attaching of the other wafer which has a port plugged with a deposited layer on its external surface. The deposition of the layer may be performed in a very low pressure environment, thus assuring the same kind of environment in the sealed chamber. The chamber may enclose at least one device such as a thermoelectric sensor, bolometer, emitter or other kind of device. The wafer-pair typically will have numerous chambers, with devices, respectively, and may be divided into a multiplicity of chips.

UP - 2000-13

1/1 LGST - ©LEGSTAT

PN - US 6036872 [US6036872]

AP - US 52645/98 19980331 [1998US-0052645]

DT - US-P

ACT - 19980331 US/AE-A

APPLICATION DATA (PATENT)

US 52645/98 19980331 [1998US-0052645]

20000314 US/A

PATENT

20020326 US/RF

REISSUE APPLICATION FILED

20011203

UP - 2002-14

1/1 CRXX - @CLAIMS/RRX

PN - 6,036,872 A 20000314 [US6036872]

PA - Honeywell Inc

ACT - 20011203 REISSUE REQUESTED

ISSUE DATE OF O.G.: 20020326

REISSUE REQUEST NUMBER: 10/007288

EXAMINATION GROUP RESPONSIBLE FOR REISSUEPROCESS: 1753

Reissue Patent Number:

1/1 PAST - ©Thomson Derwent

AN - 200213-001635

PN - 6036872 A [US6036872]

OG - 2002-03-26

ACT - REISSUE APPLICATION FILED

Query/Command: FILE INPADOC

PLUSPAT - Time in minutes : 0,70 The cost estimation below is based on Questel's standard price list Estimated cost : 1.54 USD Records displayed and billed Estimated cost : 1.10 USD Cost estimated for the last database search : 2.64 USD Estimated total session cost 3.23 USD - Time in minutes : The cost estimation below is based on Questel's standard price list Estimated cost : 0.15 USD Records displayed and billed Estimated cost : 0.57 USD Legal-Status informations Estimated cost : 4.92 USD Cost estimated for the last database search: 5.64 USD Estimated total session cost 8.87 USD - Time in minutes : 0,07 The cost estimation below is based on Questel's standard price list Estimated cost : 0.10 USD Records displayed and billed : 1 Estimated cost : 5.00 USD Legal-Status informations Estimated cost : 4.92 USD Cost estimated for the last database search : 10.02 USD Estimated total session cost 18.89 USD - Time in minutes: 0,06 The cost estimation below is based on Questel's standard price list Estimated cost : 0.11 USD Records displayed and billed :

Estimated cost : 5.61 USD Legal-Status informations Estimated cost : 4.92 USD Cost estimated for the last database search : 10.64 USD

Estimated total session cost 29.53 USD

- Time in minutes : 0,02

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Selected file: INPADOC

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Search statement 1

Query/Command: FAM US6036872/PN

1 Patent Groups

** SS 1: Results 5

Search statement 2

Query/Command: FAMSTATE NONSTOP

1/5 INPADOC - @INPADOC

PN CA 2326677 AA 19991007 [CA2326677]

A METHOD OF MAKING A WAFER-PAIR HAVING SEALED CHAMBERS TI

LA **ENG**

WOOD R ANDREW [US]; RIDLEY JEFFREY A [US]; HIGASHI ROBERT E [US] IN

PA HONEYWELL INC (US)

CA 2326677/99-A 19990330 [1999CA-2326677] AP

PR US 52645/98-A 19980331 [1998US-0052645]

WO 9906890/99(US)-W 19990330 [1999WO-US06890]

IC H01L-027/16; G01J-005/20

1/1 LEGALI - ©LEGSTAT

PN CA 2326677 [CA2326677]

DT CA-P

ACTE -20000929 CA/REFW-P

CORRESPONDS TO PCT APPLICATION

<WO 9950913> [WO9950913]

UP 2001-11 2/5 INPADOC - ©INPADOC

PN - EP 1070353 A1 20010124 [EP1070353]

TI - A METHOD FOR MAKING A WAFER-PAIR HAVING SEALED CHAMBERS

LA - ENG

IN - WOOD R ANDREW [US]; RIDLEY JEFFREY A [US]; HIGASHI ROBERT E [US]

PA - HONEYWELL INC [US]

AP - EP 99914273/99-A 19990330 [1999EP-0914273]

PR - WO 9906890/99(US)-W 19990330 [1999WO-US06890]

US 52645/98-A 19980331 [1998US-0052645]

IC - H01L-027/16; G01J-005/20

DS - DE* FR* GB*

1/1 LEGALI - ©LEGSTAT

PN - EP 1070353 [EP1070353]

AP - EP 99914273/99 19990330 [1999EP-0914273]

DT - EP-P

ACTE - 19990330 EP/AE-A

EP-APPLICATION

EP 99914273/99 19990330 [1999EP-0914273]

20010124 EP/AK-A1 [+]

DESIGNATED CONTRACTING STATES IN AN APPLICATION WITH SEARCH

REPORT: DE FR GB

20010124 EP/A1 [+]

PUBLICATION OF APPLICATION WITH SEARCH REPORT

20010124 EP/17P [+]

REQUEST FOR EXAMINATION FILED

20000928

UP - 2001-04

3/5 INPADOC - @INPADOC

PN - JP 2002510865 T2 20020409 [JP2002510865]

AP - JP 2000541738/00-A 19990330 [2000JP-0541738]

PR - US 52645/98-A 19980331 [1998US-0052645]

WO 9906890/99(US)-W 19990330 [1999WO-US06890]

IC - H01L-037/02; G01J-001/02

4/5 INPADOC - @INPADOC

PN - US 6036872 A 20000314 [US6036872]

TI - METHOD FOR MAKING A WAFER-PAIR HAVING SEALED CHAMBERS

IN - WOOD R ANDREW [US]; RIDLEY JEFFREY A [US]; HIGASHI ROBERT E [US]

PA - HONEYWELL INC [US]

AP - US 52645/98-A 19980331 [1998US-0052645]

PR - US 52645/98-A 19980331 [1998US-0052645]

IC - C23F-001/00

1/1 LEGALI - ©LEGSTAT

PN - US 6036872 [US6036872]

AP - US 52645/98 19980331 [1998US-0052645]

DT - US-P

ACTE - 19980331 US/AE-A

APPLICATION DATA (PATENT)

US 52645/98 19980331 [1998US-0052645]

20000314 US/A

PATENT

20020326 US/RF

REISSUE APPLICATION FILED

20011203

UP - 2002-14

5/5 INPADOC - ©INPADOC

PN - WO 9950913 A1 19991007 [WO9950913]

TI - A METHOD OF MAKING A WAFER-PAIR HAVING SEALED CHAMBERS

LA - ENG

IN - WOOD R ANDREW; RIDLEY JEFFREY A; HIGASHI ROBERT E

PA - HONEYWELL INC [US]

AP - WO US 9906890/99(US)-A 19990330 [1999WO-US06890]

PR - US 52645/98-A 19980331 [1998US-0052645]

IC - H01L-027/16; G01J-005/20

DS - CA* JP* AT BE CH CY DE DK ES FI FR GB GR IE IT LU MC NL PT SE

1/3 LEGALI - ©LEGSTAT

PN JP 541738/2000

AP JP 541738/2000 0 [2000JP-0541738]

DT JP-A

ACTE -20001002 JP/REFW-P

CORRESPONDS TO PCT APPLICATION

<WO 9950913> WO9950913

UP 2002-09

2/3 LEGALI - ©LEGSTAT

PN CA 2326677 [CA2326677]

DT CA-P

ACTE -20000929 CA/REFW-P

CORRESPONDS TO PCT APPLICATION

<WO 9950913> [WO9950913]

UP 2001-11

3/3 LEGALI - ©LEGSTAT

PN WO 9950913 [WO9950913]

WO 9906890/99(US) 19990330 [1999WO-US06890] AP

DT WO-P

ACTE -19990330 WO/AE-A

APPLICATION DATA

WO 9906890/99(US) 19990330 [1999WO-US06890]

19991007 WO/AK-A1 [+]

DESIGNATED STATES CITED IN A PUBLISHED APPLICATION WITH SEARCH **REPORT**

СА ЈР

19991007 WO/AL-A1 [+]

DESIGNATED COUNTRIES FOR REGIONAL PATENTS CITED IN A PUBLISHED APPLICATION WITH SEARCH REPORT

AT BE CH CY DE DK ES FI FR GB GR IE IT LU MC NL PT SE

19991007 WO/A1 [+]

PUBLICATION OF THE INTERNATIONAL APPLICATION WITH THE

INTERNATIONAL SEARCH REPORT

19991201 WO/121

EP: THE EPO HAS BEEN INFORMED BY WIPO THAT EP WAS DESIGNATED IN THIS APPLICATION

19991216 WO/DFPE

REQUEST FOR PRELIMINARY EXAMINATION FILED PRIOR TO EXPIRATION

OF 19TH MONTH FROM PRIORITY DATE

20000929 WO/ENP-AA

20000929 WO/ENP-AA ENTRY INTO THE NATIONAL PHASE IN: <CA 2326677>

20001002 WO/ENP-A ENTRY INTO THE NATIONAL PHASE IN: <JP 00541738>

UP - 2002-09

PATNO IS 6036872

DATE: SEPTEMBER 11, 2002 LIBRARY: PATENT FILE: ALL

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For further explanation, press the H key (for HELP) and then the ENTER key.

LEVEL 1 - 1 PATENT

i . .

1. 6036872 , March 14, 2000 , Method for making a wafer-pair having sealed chambers , Wood, R. Andrew, Bloomington, MN; Ridley, Jeffrey A., Burnsville, MN; Higashi, Robert E., Shorewood, MN, 00052645 (), Honeywell Inc., Minneapolis, MN

CORE TERMS: wafer, layer, vacuum, sub, detector, chamber, cavity, deposited, angstrom, port ...

LEVEL 1 - 1 OF 1 PATENT

UNITED STATES PATENT AND TRADEMARK OFFICE GRANTED PATENT

6036872

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March 14, 2000

Method for making a wafer-pair having sealed chambers

REISSUE: December 3, 2001 - Reissue Application filed Dec. 3, 2001 (O.G. Mar. 26, 2002) Ex. Gp.: 1753; Re. S.N. 10/007,288March 26, 2002

APPL-NO: 00052645 ()

FILED-DATE: March 31, 1998

GRANTED-DATE: March 14, 2000

CORE TERMS: wafer, layer, vacuum, sub, detector, chamber, cavity, deposited,

angstrom, port ...

ENGLISH-ABST:

. N

A method for fabricating a wafer-pair having at least one recess in one wafer and the recess formed into a chamber with the attaching of the other wafer which has a port plugged with a deposited layer on its external surface. The deposition of the layer may be performed in a very low pressure environment, thus assuring the same kind of environment in the sealed chamber. The chamber may enclose at least one device such as a thermoelectric sensor, bolometer, emitter or other kind of device. The wafer-pair typically will have numerous chambers, with devices, respectively, and may be divided into a multiplicity of

6036872 OR 6,036,872

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